# CDCV857A 2.5-V PHASE LOCK LOOP CLOCK DRIVER

SCAS667A - APRIL 2001 - REVISED AUGUST 2002

- **Phase-Lock Loop Clock Driver for Double Data-Rate Synchronous DRAM Applications**
- **Spread Spectrum Clock Compatible**
- Operating Frequency: 60 to 180 MHz
- Low Jitter (cyc-cyc): ±50 ps
- **Distributes One Differential Clock Input to Ten Differential Outputs**
- Three-State Outputs When the Input Differential Clocks Are <20 MHz
- **Operates From Dual 2.5-V Supplies**
- Available in a 48-Pin TSSOP Package or 56-Ball MicroStar Junior™ BGA Package
- Consumes < 200-µA Quiescent Current
- External Feedback PIN (FBIN, FBIN) Are Used to Synchronize the Outputs to the **Input Clocks**

### description

The CDCV857A is a high-performance, low-skew, low-jitter zero delay buffer that distributes a differential clock input pair (CLK,  $\overline{\text{CLK}}$ ) to ten differential pairs of clock outputs (Y[0:9],  $\overline{\text{Y[0:9]}}$ ) and one differential pair of feedback clock output (FBOUT, FBOUT). The clock outputs are controlled by the clock inputs (CLK, CLK), the feedback clocks (FBIN, FBIN), and the analog power input (AVDD). When PWRDWN is high, the outputs switch in phase and frequency with CLK. When PWRDWN is low, all outputs are disabled to high impedance state (3-state), and the PLL is shut down (low power mode). The device also enters this low power mode when the input frequency falls below a suggested detection frequency that is below 20 MHz (typical 10 MHz). An input frequency detection circuit will detect the low frequency condition and after applying a >20 MHz input signal this detection circuit turns on the PLL again and enables the outputs.

When  $AV_{DD}$  is strapped low, the PLL is turned off and bypassed for test purposes. The CDCV857A is also able to track spread spectrum clocking for reduced EMI.

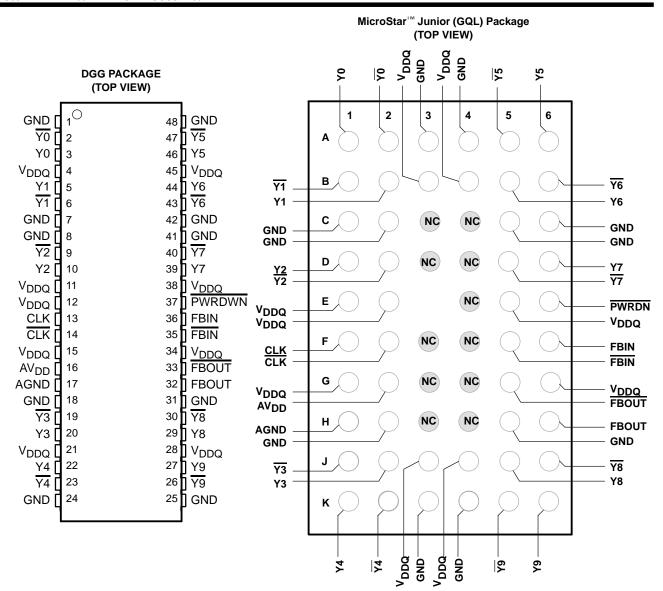
Since the CDCV857A is based on PLL circuitry, it requires a stabilization time to achieve phase-lock of the PLL. This stabilization time is required following power up. The CDCV857A is characterized for operation from 0°C to 85°C.



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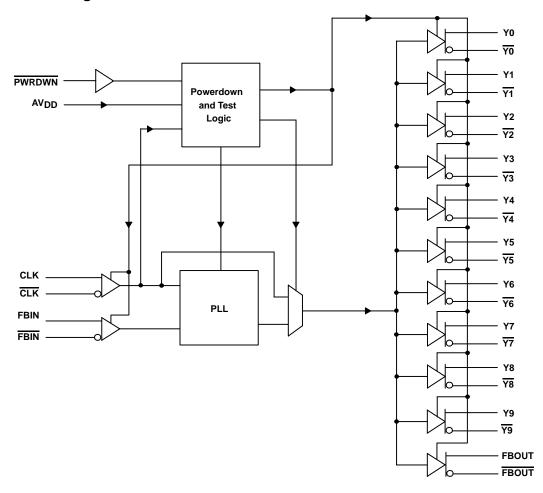




# FUNCTION TABLE (Select Functions)

	INPUTS	3			OU.	TPUTS		PLL
AV <sub>DD</sub>	AV <sub>DD</sub> PWRDWN CI		CLK	Y[0:9]	Y[0:9]	FBOUT	FBOUT	
GND	Н	L	Н	L	Н	L	Н	Bypassed/Off
GND	Н	Н	L	Н	L	Н	L	Bypassed/Off
Х	L	L	Н	Z	Z	Z	Z	Off
Х	L	Н	L	Z	Z	Z	Z	Off
2.5 V (nom)	Н	L	Н	L	Н	L	Н	On
2.5 V (nom)	Н	Н	Ĺ	Н	Ĺ	Н	Ĺ	On
2.5 V (nom)	Х	<20 MHz	<20 MHz	Z	Z	Z	Z	Off

# functional block diagram



#### **Terminal Functions**

Т	ERMINAL			DESCRIPTION
NAME	DGG	GQL		DESCRIPTION
AGND	17	H1		Ground for 2.5-V analog supply
$AV_{DD}$	16	G2		2.5-V Analog supply
CLK, CLK	13, 14	F1, F2	-1	Differential clock input
FBIN, FBIN	35, 36	F5, F6	1	Feedback differential clock input
FBOUT, FBOUT	32, 33	H6, G5	0	Feedback differential clock output
GND	1, 7, 8, 18, 24, 25, 31, 41, 42, 48	A3, A4, C1, C2, C5, C6, H2, H5, K3, K4		Ground
PWRDWN	37	E6	I	Output enable for Y and $\overline{Y}$
VDDQ	4, 11, 12, 15, 21, 28, 34, 38, 45	B3, B4, E1, E2, E5, G1, G6, J3, J4		2.5-V Supply
Y[0:9]	3, 5, 10, 20, 22, 27, 29, 39, 44, 46	A1, B2, D1, J2, K1, A6, B5, D6, J5, K6	0	Buffered output copies of input clock, CLK
<u>Y[0:9]</u>	2, 6, 9, 19, 23, 26, 30, 40, 43, 47	A2, B1, D2, J1, K2, A5, B6, D5, J6, K5	0	Buffered output copies of input clock, CLK

# absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V <sub>DDQ</sub> , AV <sub>DD</sub>	0.5 V to 3.6 V
Input voltage range, V <sub>I</sub> (see Notes 1 and 2)	0.5 V to V <sub>DDQ</sub> 0.5 V
Output voltage range, VO (see Notes 1 and 2)	0.5 V to V <sub>DDQ</sub> 0.5 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{DDQ}$ )	±50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{DDO}$ )	±50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{DDO})$	±50 mA
Continuous current to GND or V <sub>DDQ</sub>	±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3): DGG package	89°C/W
GQL package	137.6°C/W
Storage temperature range T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
  - 2. This value is limited to 3.6 V maximum.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



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## recommended operating conditions (see Note 4)

			MIN	TYP	MAX	UNIT	
Supply voltage, V <sub>DDQ</sub> , AV <sub>DD</sub>			2.3		2.7	V	
Low level input voltage Ve	CLK,	CLK, FBIN, FBIN			V <sub>DDQ</sub> /2 – 0.18	V	
Low level input voltage, V <sub>IL</sub>	PWR	RDWN	-0.3		2.7	V	
High level input voltage, VIH	CLK, CLK, FBIN, FBIN V <sub>DDQ</sub> /2 + 0.18			V			
High level input voltage, VIH	PWR	RDWN	1.7		2.7 V <sub>DDQ</sub> /2 - 0.18 0.7 V <sub>DDQ</sub> + 0.3 V <sub>DDQ</sub> + 0.6 V <sub>DDQ</sub> + 0.6 V <sub>DDQ</sub> /2 + 0.2 V <sub>DDQ</sub> /2 + 0.2 12 4	V	
DC input signal voltage (see Note 5)			-0.3		$V_{DDQ}$	V	
ifferential input signal voltage, V <sub>ID</sub> (see Note 6)	DC	CLK, FBIN	0.36		V <sub>DDQ</sub> + 0.6	V	
Dillerential input signal voltage, VID (see Note o)	AC	CLK, FBIN	0.7		2.7 V <sub>DDQ</sub> /2 - 0.18 0.7 V <sub>DDQ</sub> + 0.3 V <sub>DDQ</sub> + 0.6 V <sub>DDQ</sub> + 0.6 V <sub>DDQ</sub> /2 + 0.2 V <sub>DDQ</sub> /2 + 0.2 12 4	V	
Output differential cross-voltage, V <sub>OX</sub> (see Note 7)			V <sub>DDQ</sub> /2 – 0.2	V <sub>DDQ</sub> /2	V <sub>DDQ</sub> /2 + 0.2	V	
Input differential pair cross-voltage, $V_{IX}$ (see Note 7	)		V <sub>DDQ</sub> /2 – 0.2		$V_{DDQ}/2 + 0.2$	V	
High-level output current, IOH					-12	mA	
Low-level output current, IOL	w-level output current, IOL				12	mA	
Input slew rate, SR			1		4	V/ns	
Operating free-air temperature, TA			0		85	°C	

NOTES: 4. Unused inputs must be held high or low to prevent them from floating.

- 5. DC input signal voltage specifies the allowable dc execution of differential input.
- 6. Differential input signal voltage specifies the differential voltage |VTR VCP| required for switching, where VTR is the true input level and VCP is the complementary input level.
- 7. Differential cross-point voltage is expected to track variations of VCC and is the voltage at which the differential signals must be crossing.



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### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST Co	ONDITIONS	MIN	TYP	MAX	UNIT	
VIK	Input voltage	All inputs	$V_{DDQ} = 2.3 V,$	I <sub>I</sub> = -18 mA			-1.2	V	
V/0	High-level outp	ut voltogo	V <sub>DDQ</sub> = min to max	x, I <sub>OH</sub> = -1 mA	V <sub>DDQ</sub> - 0.1			V	
VOH	High-level outp	ut voltage	$V_{DDQ} = 2.3 V,$	I <sub>OH</sub> = -12 mA	1.7			V	
\/o:	Low-level outpu	ıt voltago	V <sub>DDQ</sub> = min to max	x, I <sub>OL</sub> = 1 mA			0.1	V	
VOL	Low-level outpo	ii voitage	$V_{DDQ} = 2.3 V,$	$I_{OL}$ = 12 mA			0.6	V	
loh	High-level outp	ut current	$V_{DDQ} = 2.3 V,$	V <sub>O</sub> = 1 V	-18	-32		mA	
IOL	Low-level outpu	ıt current	$V_{DDQ} = 2.3 V,$	V <sub>O</sub> = 1.2 V	26	35		mA	
VO	Output voltage	swing	Differential outputs a	are terminated with	1.1		V <sub>DDQ</sub> - 0.4		
Vox	Output different cross-voltage§	ial	120 $\Omega$	are terriiriated with	V <sub>DDQ</sub> /2 – 0.2	V <sub>DDQ</sub> /2	V <sub>DDQ</sub> /2 + 0.2	V	
lį	Input current		$V_{DDQ} = 2.7 V,$	V <sub>I</sub> = 0 V to 2.7 V			±10	μΑ	
loz	High-impedanc output current	e-state	V <sub>DDQ</sub> = 2.7 V,	V <sub>O</sub> = V <sub>DDQ</sub> or GND			±10	μΑ	
I <sub>DDPD</sub>	Power down cu V <sub>DDQ</sub> + AV <sub>DD</sub>		CLK and $\overline{\text{CLK}} = 0 \text{ M}$ $\Sigma$ of IDD and AIDD	IHz; PWRDWN = Low;		100	200	μΑ	
			Differential outputs	f <sub>O</sub> = 180 MHz		275	330		
1	Dynamic currer	ot on \/	terminated with 120 $\Omega$ /CL = 14 pF	f <sub>O</sub> = 167 MHz		250	300	mA	
IDD	Dynamic currer	it on vDDQ	Differential outputs	f <sub>O</sub> = 180 MHz		225	275	IIIA	
			terminated with $120 \Omega/CL = 0 pF$	f <sub>O</sub> = 167 MHz		210	250		
A1	Cumply augrent	on A\/	f <sub>O</sub> = 180 MHz			10	12	A	
AIDD	Supply current	OU AADD	f <sub>O</sub> = 167 MHz		8 10		mA		
Cl	Input capacitan	ce	V <sub>CC</sub> = 2.5 V	V <sub>I</sub> = V <sub>CC</sub> or GND	2	2.5	3	рF	
CO	Output capacita	ince	V <sub>CC</sub> = 2.5 V	$V_O = V_{CC}$ or GND	2.5	3	3.5	pF	

## timing requirements over recommended ranges of supply voltage and operating free-air temperature

		MIN	MAX	UNIT
f =	Operating clock frequency	60	180	MHz
fCLK	Application clock frequency	60	100	IVITIZ
	Input clock duty cycle	40%	60%	
	Stabilization time¶ (PLL mode)		10	μs
	Stabilization time¶ (Bypass mode)		30	ns

<sup>¶</sup> Time required for the integrated PLL circuit to obtain phase lock of its feedback signal to its reference signal. For phase lock to be obtained, a fixed-frequency, fixed-phase reference signal must be present at CLK. Until phase lock is obtained, the specifications for propagation delay, skew, and jitter parameters given in the switching characteristics table are not applicable. This parameter does not apply for input modulation under SSC application.



 $<sup>\</sup>uparrow$  All typical values are at respective nominal V<sub>DDQ</sub>.  $\uparrow$  The value of V<sub>OC</sub> is expected to be |VTR + VCP|/2. In case of each clock directly terminated by a 120- $\Omega$  resistor, where VTR is the true input signal voltage and VCP is the complementary input signal voltage.

<sup>§</sup> Differential cross-point voltage is expected to track variations of VDDQ and is the voltage at which the differential signals must be crossing.

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# switching characteristics

	PARAMETER	TES	ST CONDITIONS	MIN TY	P <sup>†</sup> MAX	UNIT
<sup>t</sup> PLH <sup>‡</sup>	Low to high level propagation delay time	Test mod	e/CLK to any output		4.5	ns
tPHL <sup>‡</sup>	High-to low level propagation delay time	Test mod	e/CLK to any output		4.5	ns
<b></b> . 8	litter (neried) Coe Figure 6	66 MHz		-55	55	ps
<sup>t</sup> jit(per) <sup>§</sup>	Jitter (period), See Figure 6	100/133/	167/180 MHz	-35	35	ps
<b></b> . 8	litter (evale to evale). See Figure 2	Test mode/CLK to any ou 66 MHz 100/133/167/180 MHz 66 MHz 100/133/167/180 MHz 66 MHz 100/133/167/180 MHz 66 MHz 100/133/167/180 MHz SSC off 66 MHz 100/133 MHz		-60	60	
<sup>t</sup> jit(cc) <sup>§</sup>	Jitter (cycle-to-cycle), See Figure 3	100/133/	de/CLK to any output de/CLK to any output de/CLK to any output 3/167/180 MHz 3/167/180 MHz 66 MHz 100/133 MHz 167/180 MHz 167/180 MHz 3/167/180 MHz	-50	50	ps
<b>.</b>	Lak period itter Con Figure 7	66 MHz		-100	100	
<sup>t</sup> jit(hper) <sup>§</sup>	Half-period jitter, See Figure 7	100/133/		-75	75	ps
tslr(i)	Input clock slew rate, See Figure 8			1	4	V/ns
tslr(o)	Output clock slew rate, See Figure 8			1	2	V/ns
			66 MHz	-180	180	_
		SSC off	100/133 MHz	-130	130	
<b>.</b>	Dynamic phase offset (this includes jitter), See		167/180 MHz	-90	90	
<sup>t</sup> d(Ø) <sup>§</sup>	Figure 4(b)		66 MHz	-230	230	ps
		SSC on	100/133 MHz	-170	170	
			167/180 MHz	-100	100	
t	Statio phage offeet See Figure 4(a)	66 MHz		-150	150	20
<sup>t</sup> (Ø)	Static phase offset, See Figure 4(a)	100/133/	167/180 MHz	-100	100	ps
tsk <sub>(O)</sub> ¶	Output skew, See Figure 5				75	ps
tr, tf	Output rise and fall times (20% – 80%)	Load: 120	0 Ω/14 pF	650	900	ps

<sup>†</sup> All typical values are at a respective nominal V<sub>DDQ</sub>.
‡ Refers to transition of noninverting output.
§ This parameter is assured by design but can not be 100% production tested.
¶ All differential output pins are terminated with 120 Ω/14 pF.

#### PARAMETER MEASUREMENT INFORMATION

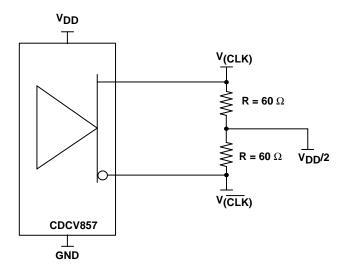


Figure 1. IBIS Model Output Load (used for slew rate measurement)

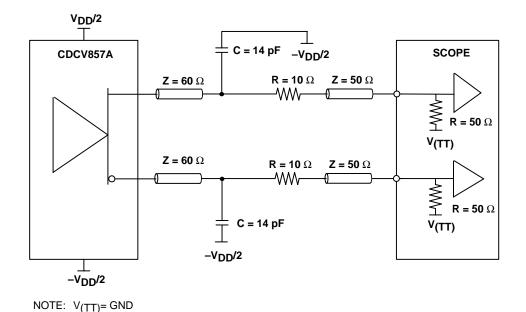


Figure 2. Output Load Test Circuit

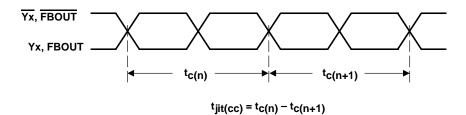
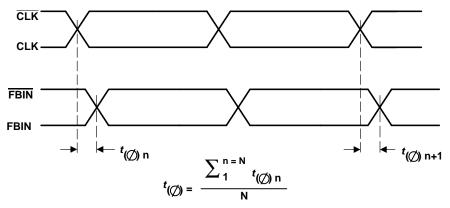


Figure 3. Cycle-to-Cycle Jitter

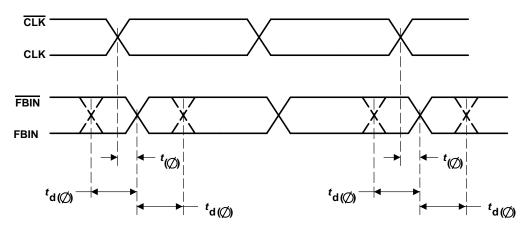


### PARAMETER MEASUREMENT INFORMATION



(N is a large number of samples)

(a) Static Phase Offset



(b) Dynamic Phase Offset

Figure 4. Phase Offset

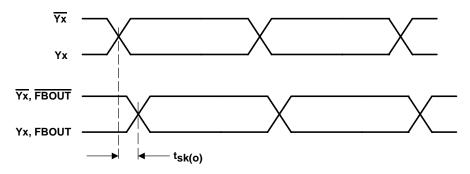


Figure 5. Output Skew

#### PARAMETER MEASUREMENT INFORMATION

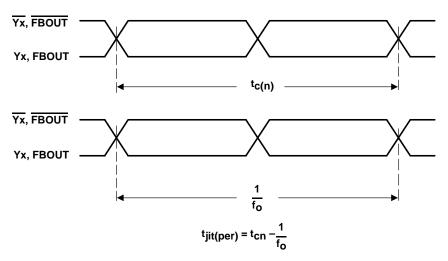


Figure 6. Period Jitter

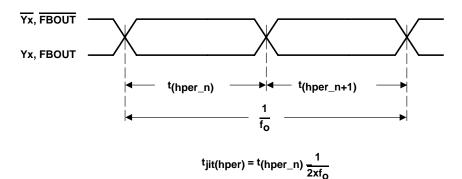


Figure 7. Half-Period Jitter

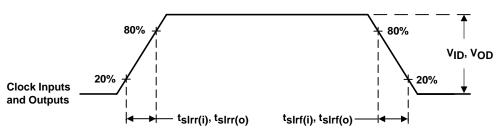


Figure 8. Input and Output Slew Rates

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
CDCV857ADGG	NRND	Production	TSSOP (DGG)   48	40   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 85	CDCV857A
CDCV857ADGGG4	NRND	Production	TSSOP (DGG)   48	40   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 85	CDCV857A
CDCV857ADGGR	NRND	Production	TSSOP (DGG)   48	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	0 to 85	CDCV857A

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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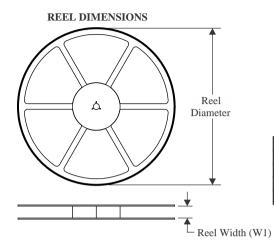
<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

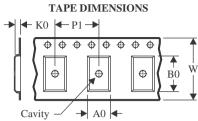
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

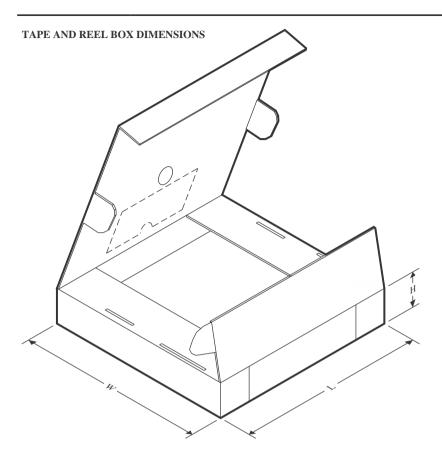


#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCV857ADGGR	TSSOP	DGG	48	2000	330.0	24.4	8.6	13.0	1.8	12.0	24.0	Q1

**PACKAGE MATERIALS INFORMATION** 

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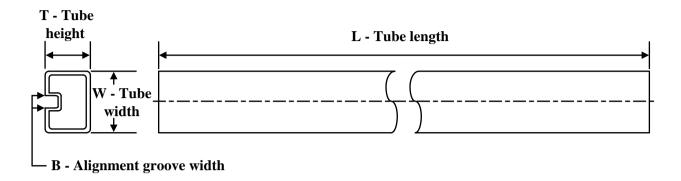
#### \*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
ı	CDCV857ADGGR	TSSOP	DGG	48	2000	356.0	356.0	45.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CDCV857ADGG	DGG	TSSOP	48	40	530	11.89	3600	4.9
CDCV857ADGGG4	DGG	TSSOP	48	40	530	11.89	3600	4.9

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